FASF

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***The 4th Molding Innovation!***

**— Reducing semiconductor mass production costs by “half”—**

# Launch of Sales of Next-Generation Compression Molding Equipment “INNOMS”


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| Company name: | TOWA CORPORATION |
| Listing: | Prime Market of Tokyo Stock Exchange |
| Securities code: | 6315 |
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TOWA Corporation will begin sales in August 2026 of INNOMS, our next-generation compression molding equipment that fundamentally transforms the way semiconductor packages are mass-produced.

“INNOMS” is TOWA’s next-generation flagship equipment, developed with the target of reducing mass-production cost by approximately 50% compared with our conventional equipment. It achieves high productivity, energy saving, and space saving—attributes that have been difficult to realize together—at a high level, and proposes a new standard in semiconductor back-end processes as equipment that changes customers’ mass-production cost structure itself.

1. Background of Development

Amid the rapid expansion of the semiconductor market, driven by the growth of generative AI and increased investment in data centers, particularly in the memory segment, semiconductors are required more than ever to simultaneously achieve “low cost,” “mass production,” and “reduction of environmental impact.”

“INNOMS” was developed in response to these market demands, with the aim of evolving the compression molding technology that we have cultivated over many years and maximizing the value generated by each piece of equipment.

It is intended not only to enhance equipment performance, but also to serve to improve the overall factory’s investment efficiency, production capacity, and environmental responsiveness, and to become a core component of next-generation mass production lines.

2. Features of the New Product (Compared with our conventional equipment)

(1) Mass production costs: approximately 50% reduction

This will significantly transform the cost structure of semiconductor package mass production.

(2) Doubling of production capacity per unit of equipment

Each piece of equipment is designed to significantly expand molding volume, achieving double the productivity of our conventional equipment.

(3) Space saving

By integrating a high-capacity press with an optimized transfer system, the equipment maintains high productivity while reducing installation footprint by 40%.

This enables greater production output even within limited factory space.

(4) Energy saving

Through comprehensive optimization of the equipment configuration and the entire molding process, power consumption is reduced by 50% and consumable materials by 25%, resulting in lower operating costs and reduced environmental impact.

(5) Support for a wide range of packages

Primarily targeting the memory segment, the equipment supports a wide variety of packages, including logic, QFN, and RF modules.

3. Going Forward

We position "INNOMS" as a strategic product symbolizing the "4th Molding Innovation," and will accelerate its deployment to the global market in earnest.

By establishing new benchmarks for cost and productivity in semiconductor mass production, we will contribute to customers' business growth and to the creation of sustainable value in the semiconductor back-end process industry.